

April 2000

FQPF16N15

150V N-Channel MOSFET

General Description

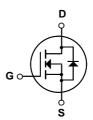
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as audio amplifire, high efficiency switching for DC/DC converters, and DC motor control, uninterrupted power supply.

Features

- 11.6A, 150V, $R_{DS(on)}$ = 0.16 Ω @V_{GS} = 10 V Low gate charge (typical 23 nC)
- Low Crss (typical 30 pF)
- · Fast switching
- · 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQPF16N15	Units	
V _{DSS}	Drain-Source Voltage		150	V	
I _D	Drain Current - Continuous (T _C = 25°C	C)	11.6	А	
	- Continuous (T _C = 100°	(C)	8.2	А	
I _{DM}	Drain Current - Pulsed	(Note 1)	46.4	А	
V _{GSS}	Gate-Source Voltage		± 25	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	230	mJ	
I _{AR}	Avalanche Current	(Note 1)	11.6	А	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	5.3	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.0	V/ns	
P _D	Power Dissipation (T _C = 25°C)		53	W	
	- Derate above 25°C		0.36	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		2.78	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	150			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.17		V/°C
I _{DSS}		V _{DS} = 150 V, V _{GS} = 0 V			1	μΑ
Zero	ero Gate Voltage Drain Current	V _{DS} = 120 V, T _C = 150°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -25 V, V _{DS} = 0 V			-100	nA
On Chr	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 5.8 A		0.123	0.16	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 5.8 A (Note 4)		8.3		S
C _{oss}	Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		145 30	190 40	pF pF
C _{oss}	Reverse Transfer Capacitance	f = 1.0 MHz				pF pF
Switch	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	V = 75 V L = 16 4 A		11	30	ns
t _r	Turn-On Rise Time	$V_{DD} = 75 \text{ V}, I_{D} = 16.4 \text{ A},$ $R_{G} = 25 \Omega$		115	240	ns
	Turn-Off Delay Time	11G - 20 s2		50	110	ns
t _{d(off)}		(1)-1-1 (1)		80	170	ns
	Turn-Off Fall Time	(Note 4, 5)				113
t _f	Turn-Off Fall Time Total Gate Charge	, , ,		23	30	nC
t _f Q _g		V _{DS} = 120 V, I _D = 16.4 A, V _{GS} = 10 V		23 4.5	30	
t _f Q _g Q _{gs}	Total Gate Charge	V _{DS} = 120 V, I _D = 16.4 A,				nC
t _f Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge	$V_{DS} = 120 \text{ V}, I_D = 16.4 \text{ A},$ $V_{GS} = 10 \text{ V}$ (Note 4, 5)		4.5		nC nC
t _f Q _g Q _{gs} Q _{gd} Drain-S	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V _{DS} = 120 V, I _D = 16.4 A, V _{GS} = 10 V (Note 4, 5)		4.5		nC nC
t _f Q _g Q _{gs} Q _{gd} Drain-S	Total Gate Charge Gate-Source Charge Gate-Drain Charge Source Diode Characteristics ar	V _{DS} = 120 V, I _D = 16.4 A, V _{GS} = 10 V (Note 4, 5) And Maximum Ratings and Forward Current		4.5		nC nC
t_f Q_g Q_{gs} Q_{gd} Drain-S t_{SM}	Total Gate Charge Gate-Source Charge Gate-Drain Charge Source Diode Characteristics ar Maximum Continuous Drain-Source Dio	V _{DS} = 120 V, I _D = 16.4 A, V _{GS} = 10 V (Note 4, 5) And Maximum Ratings and Forward Current		4.5	11.6	nC nC nC
Drain-S	Total Gate Charge Gate-Source Charge Gate-Drain Charge Source Diode Characteristics ar Maximum Continuous Drain-Source Diode Maximum Pulsed Drain-Source Diode F	V _{DS} = 120 V, I _D = 16.4 A, V _{GS} = 10 V (Note 4, 5) Add Maximum Ratings adde Forward Current Torward Current		4.5	 11.6 46.4	nC nC nC

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 2.85mH, I_{AS} = 11.6A, V_{DD} = 25V, R_G = 25 Ω , Starting T_J = 25°C 3. I_{SD} \leq 11.6A, di/dt \leq 300A/μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300μs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

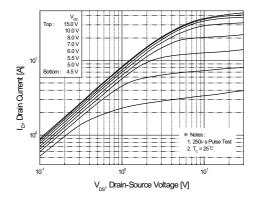


Figure 1. On-Region Characteristics

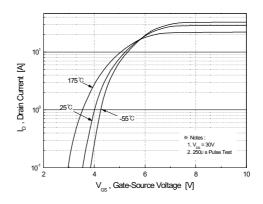


Figure 2. Transfer Characteristics

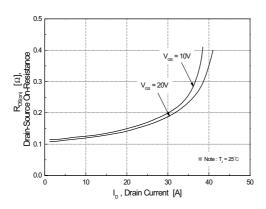


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

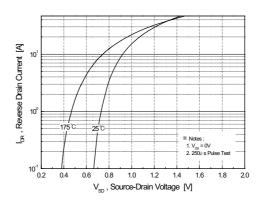


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

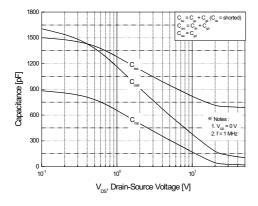


Figure 5. Capacitance Characteristics

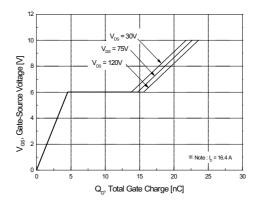
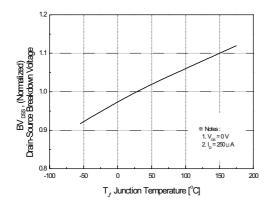


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)



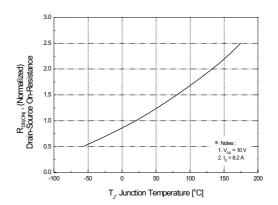
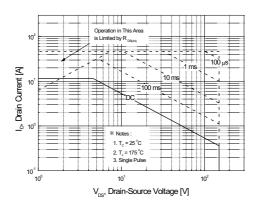


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



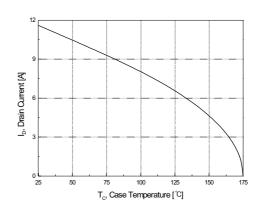


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

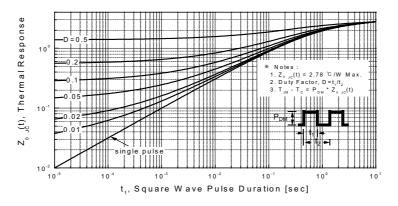
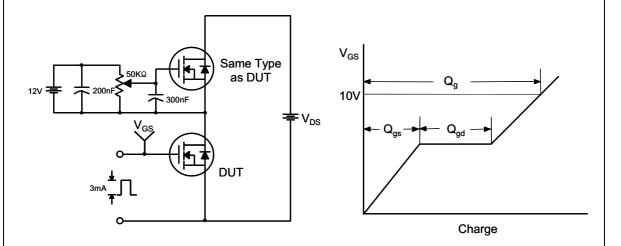


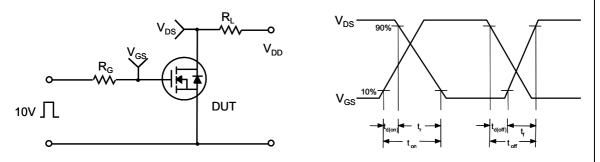
Figure 11. Transient Thermal Response Curve

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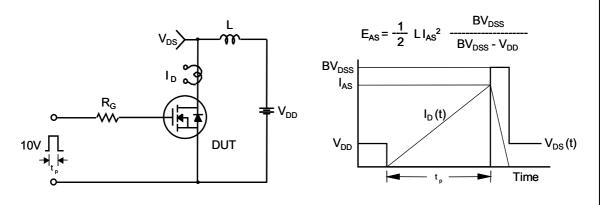
Gate Charge Test Circuit & Waveform



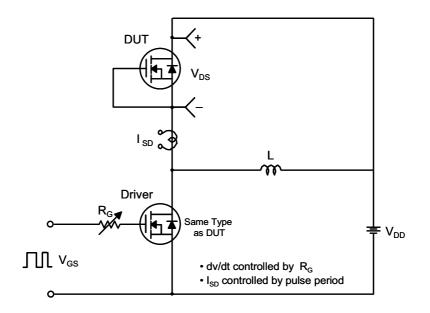
Resistive Switching Test Circuit & Waveforms

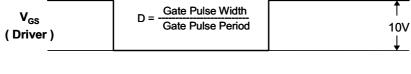


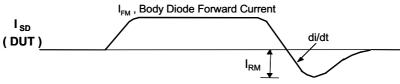
Unclamped Inductive Switching Test Circuit & Waveforms



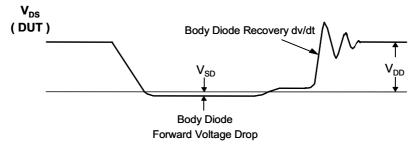
Peak Diode Recovery dv/dt Test Circuit & Waveforms



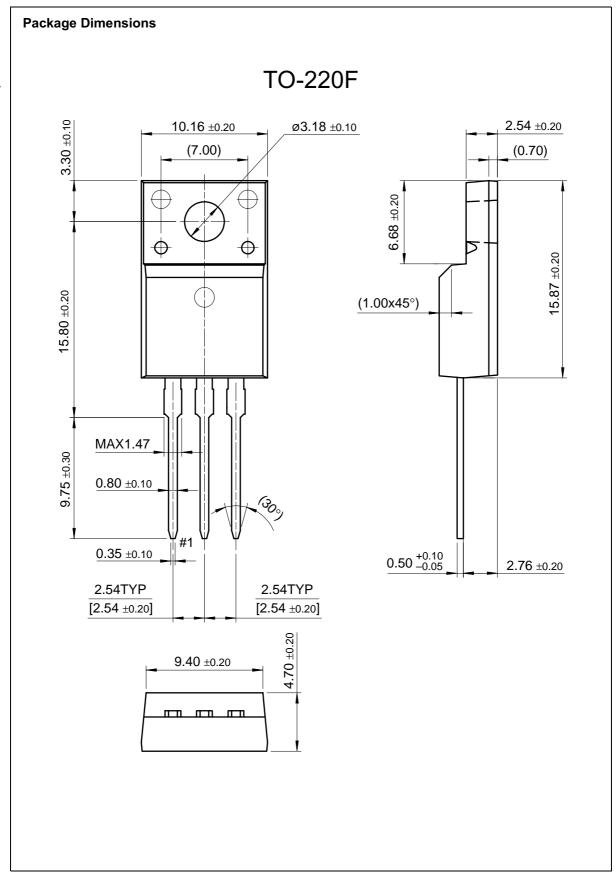




Body Diode Reverse Current



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